



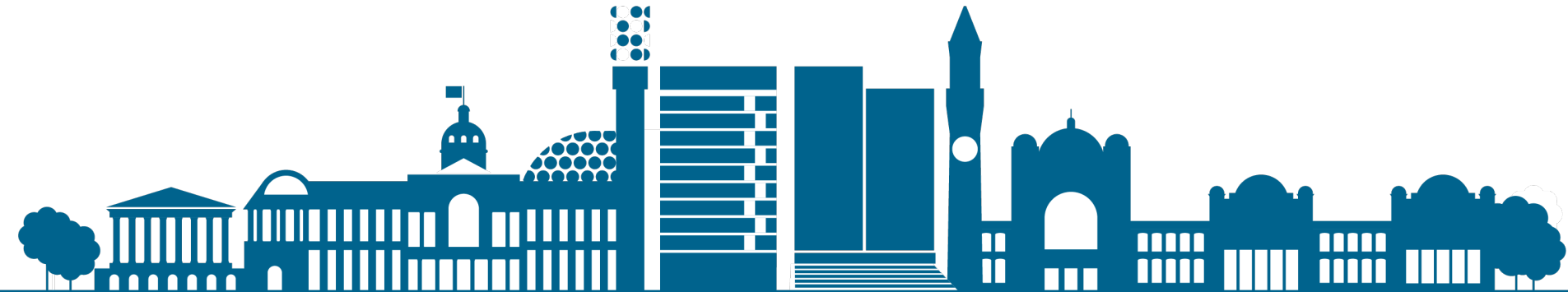
UNIVERSITY OF  
BIRMINGHAM

# Status of MAPS tracking

Laura Gonella on behalf of the EIC R&D WP1 MAPS group

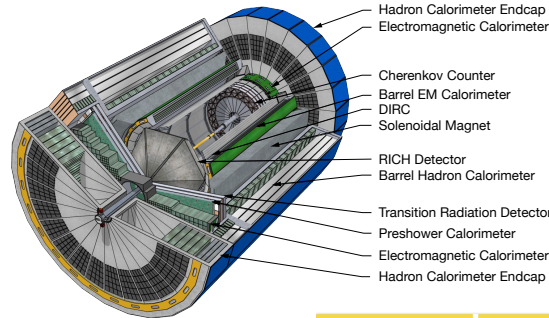
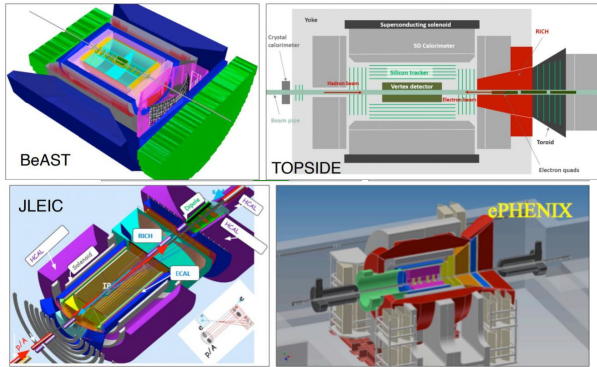
EIC UK Discussion Meeting

30 June 2022



# EIC Detector Concepts

White paper (2012, 2014), initial concepts



Yellow Report reference detector (2020), global effort of the EIC Users Group



Call for Detector proposals (2021)

**ATHENA:** A Totally Hermetic Electron-Nucleus Apparatus

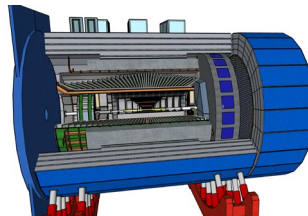
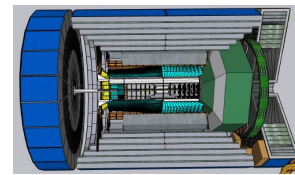
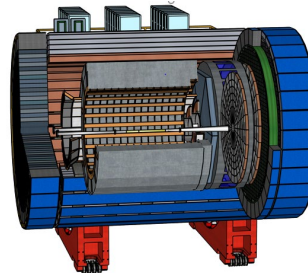
- General purpose detector inspired by YR studies, new central magnet of up to 3T

**CORE:** COmpact detectoR for the Eic

- Nearly hermetic, general purpose compact detector, 2T baseline

**ECCE:** EIC Comprehensive Chromodynamics Experiment

- General purpose detector, 1.5T BaBar magnet



2022: Merging of ECCE and ATHENA proposal strengths forming a new collaboration and a new concept for **DETECTOR 1**.

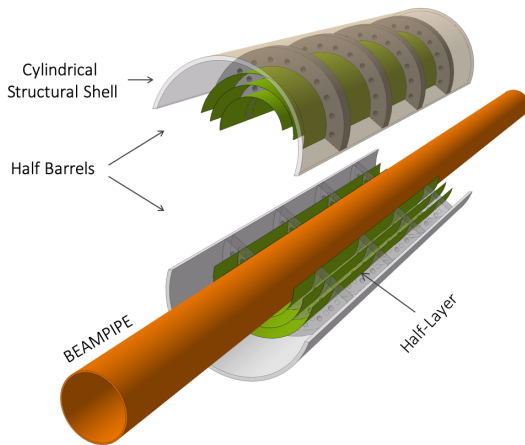
Starting point: reference detector (i.e. design).





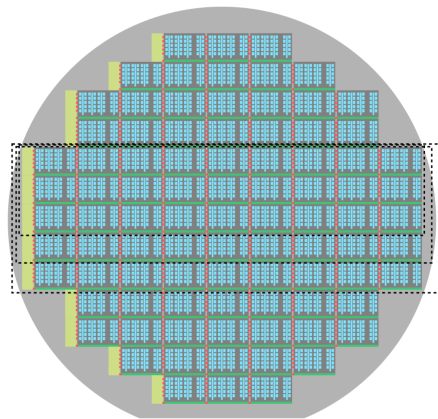
# Detector 1 Silicon Vertex and Tracker

- The EIC Detector 1 SVT concept is derived from the ALICE ITS3 technology.
- Vertex layers ITS3 like
  - **ITS3 wafer-scale stitched sensor**, thinned and bent around beam pipe.
  - No services in active area, air cooling, minimal support structure.
  - **0.05% X/X0.**

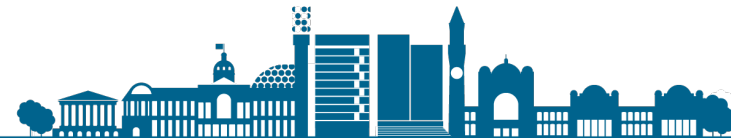
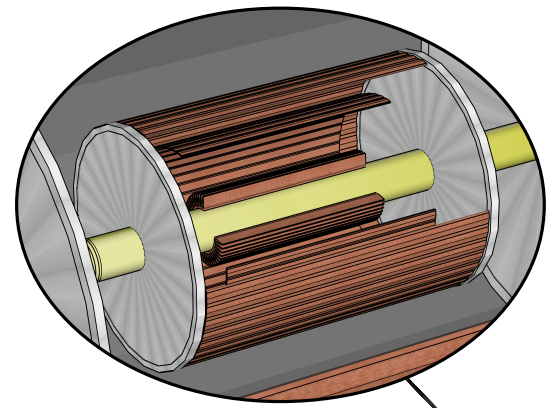


ITS3 detector layout

Stitched sensor wafer layout example



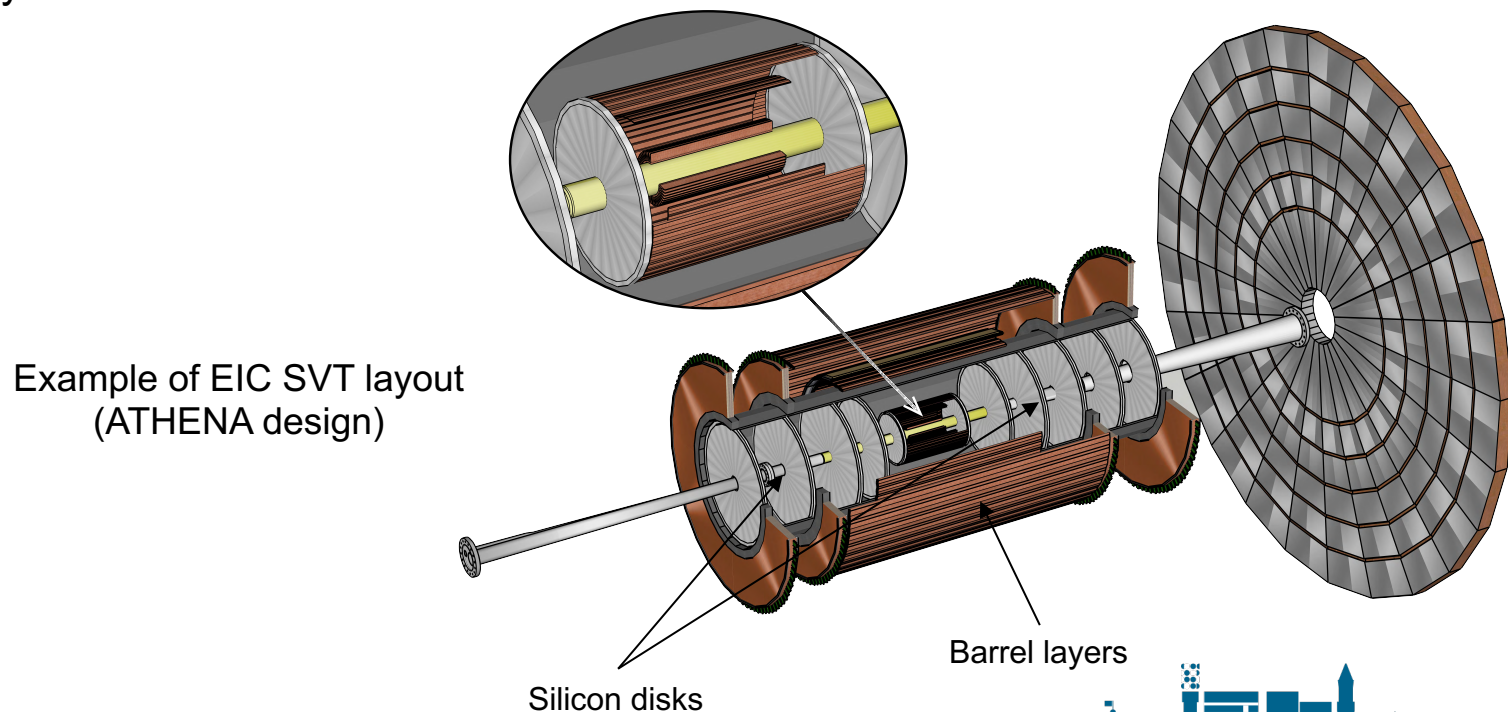
EIC Vertex Layers layout  
(as in ATHENA Proposal, same for ECCE)



# Detector 1 Silicon Vertex and Tracker

## □ Barrel layers and disks

- **EIC Large Area Sensor** (LAS), i.e. ITS3 sensor size optimised for high yield, low cost, large area coverage.
- Convectional carbon fibre support structures with integrated cooling.
- Conservative material budget estimates: 0.24%  $X/X_0$  per disk, 0.55%  $X/X_0$  per barrel layer



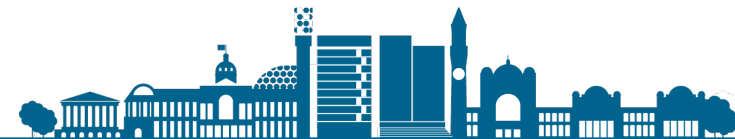
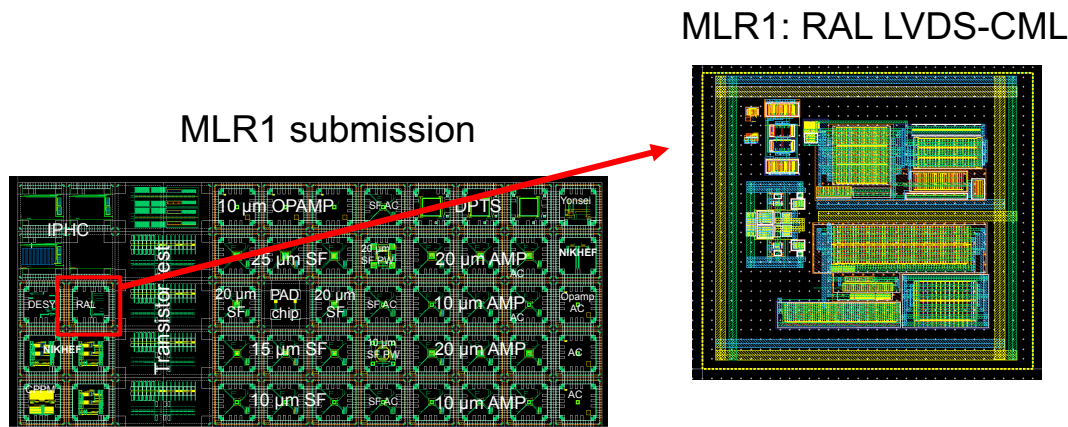
# EIC R&D WP1 MAPS

- Institutes involved:
  - Universities: Birmingham, Brunel, Lancaster, Liverpool.
  - STFC Labs: RAL, DL.
  
- Work is carried out within the **EIC Silicon Consortium and EIC project** and in collaboration with **ITS3 and the CERN EP R&D programme**.
  
- Work packages
  - WP1.1 – Sensor design
  - WP1.2 – Sensor characterisation and DAQ
  - WP1.3 – Modules and system tests
  - WP1.4 – Detector layout simulations



# WP1.1 – Sensor Design

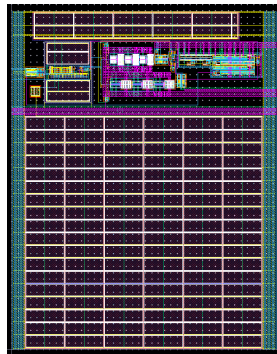
- RAL TD is actively involved in the development of **65 nm MAPS** sensor and IP blocks in collaboration with **CERN EP R&D WP1.2** and **ITS WP2**.
- Main contribution: development of high-speed data transmission IP blocks that will be used in the final version of the large area ITS3 sensor.
- **MLR1** submission Q1-2021: **LVDS receiver and CML transmitter**.



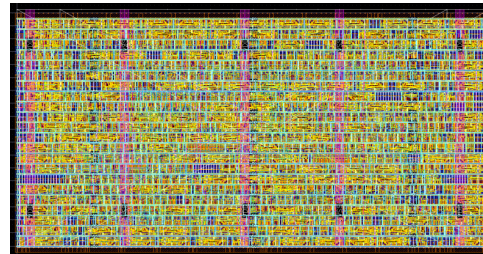
# WP1.1 – Sensor Design

- **ER1** submission Q2-2022:
  - **PLL and CML receiver**; the PLL will be integrated with the MLR1 IP blocks.
  - **I2C block**; of interest to the ITS3 large area sensor development for on-chip signal transmission.
  - **DFM cells improvements** required by the collaboration also carried out by RAL TD.

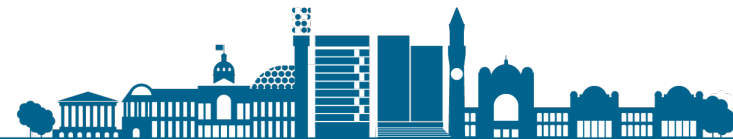
ER1: RAL PLL



ER1: I2C

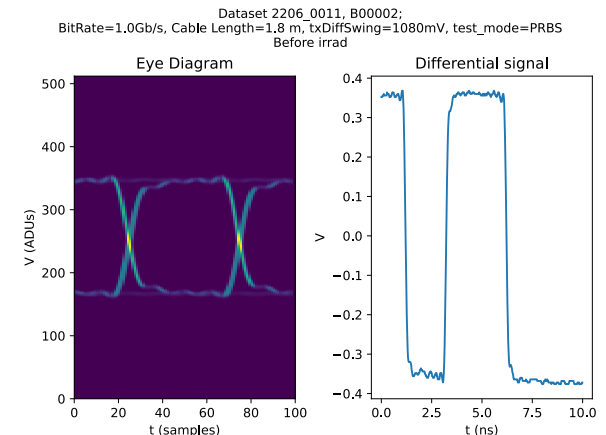
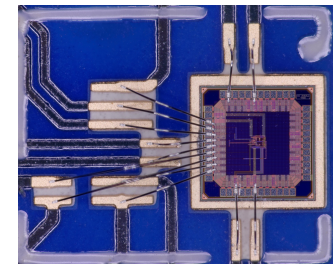
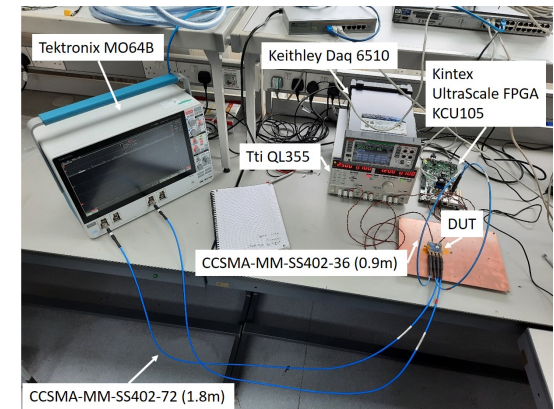


- Contributions being defined for the ITS3 ER2/EIC 1<sup>st</sup> ER in 2023.
  - RAL TD/PPD starting work on shunt regulator design for serial powering.



# WP 1.2 – Sensor Characterisation

- Structures available for characterisation are those submitted in the MLR1.
  - ITS3 Analogue and Digital Pixel test Structures (APTS, DPTS).
  - IP blocks from various institutes.
- APTS/DPTS
  - Organised within the **ITS3 WP3**.
  - BHM/LIV contributing to wire bonding of APTS sensors for testing by the ITS3 and EIC communities.
  - Waiting for ITS3 test system distribution.
- RAL IP block
  - DL/RAL TD developed testing setup.
  - Chips bonded at BHM/LIV.
  - Preliminary results from RAL/DL.
  - X-rays irradiations at CERN planned for summer.

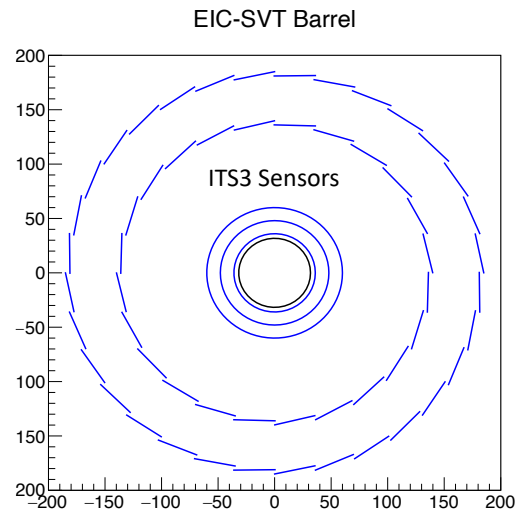
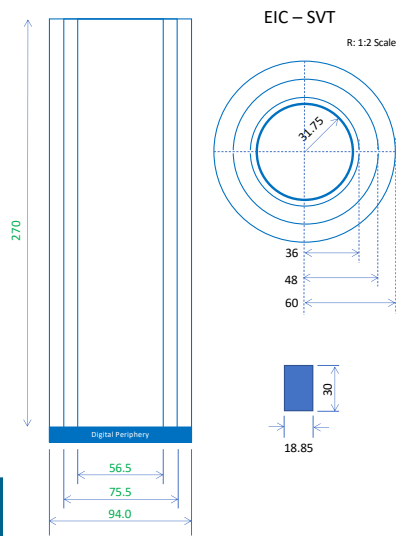




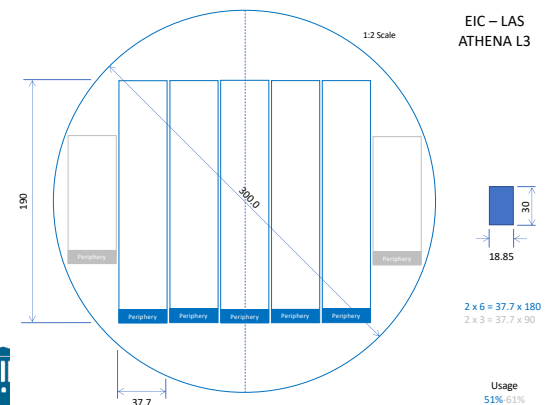
# WP1.3 – Modules and system tests

- Activities in WP1.3 are connected to the tasks in the **EIC funded eRD111 and eRD104 projects**.
  - The UK participates in: eRD111 Task 1 **Modules**, eRD111 Task 2 Staves, eRD104 Task 1 **Powering**.
  - Ongoing conceptual design and layout studies at BHM/DL.
- **Vertex layers** with ITS3 sensor, EIC LAS in **barrel layers**
  - For barrel layers consider options for sensor size to maximise use of wafer and tile staves with at most 2 sensors to keep services outside active volume.

## ITS3 sensor size and achievable EIC vertex layers radii

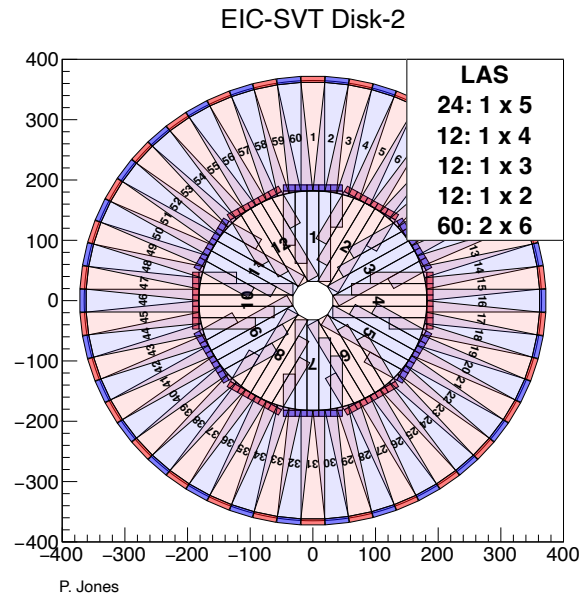
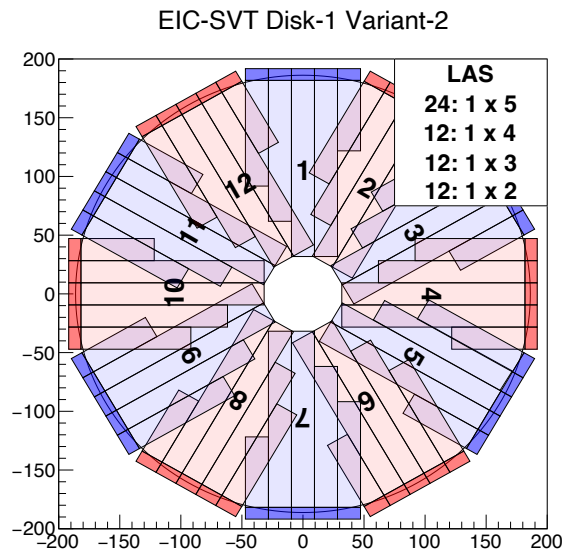


## Example study of LAS sizes to maximise wafer usage using ECCE/ATHENA radii.



# WP1.3 – Modules and system tests

- Sensor layout on **disks** challenging.
  - Maximise acceptance around beam pipe with low material
  - Current approach aims at a combination of elements common to most/all disks and an element specific to the beam-pipe opening at a particular location.

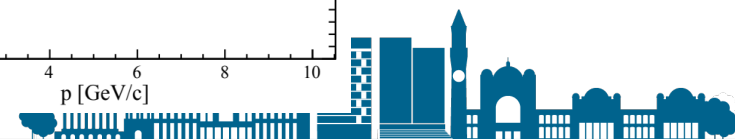
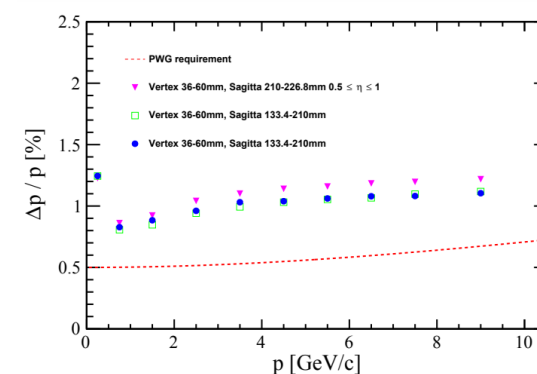
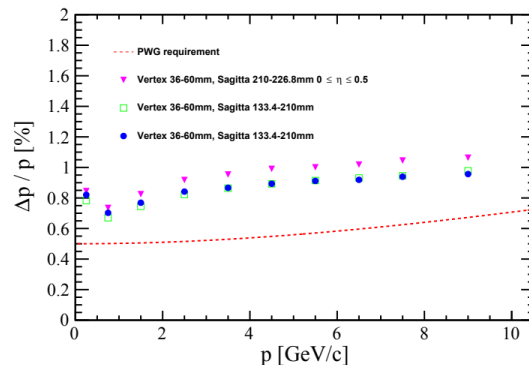
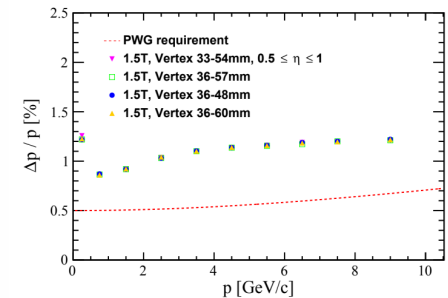
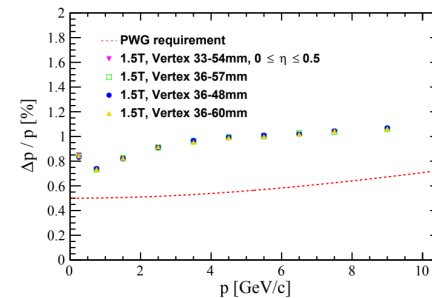
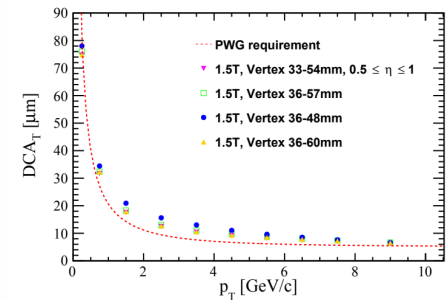
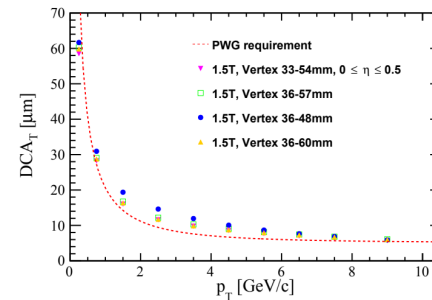


- Accompanying work on mechanics and CAD about to start.



# WP1.4 – Detector layout simulations

- Work carried out in support of the reference detector optimisation within the **EIC Detector 1 Tracking Working group**.
- Study of  $DCA_T$  and  $dp/p$  for updated reference detector design with inputs from WP1.3.
  - Updated material budget estimates and vertex layers radii.
  - Study of barrel layers position to avoid services in active area.



# Conclusion

- Through the EIC R&D funding, seven UK groups are leading the development of the Silicon Vertex and Tracking system for the EIC Detector 1.
  - Work carried out within the EIC SC, EIC project R&D, ITS3 project, CERN EP R&D programme, EIC Detector 1 tracking WG.
  
- We are contributing to the design of the next generation 65 nm MAPS and their characterisation.
  - IP blocks contributed to both MLR1 and ER1; characterisation of MLR1 RAL IP block ongoing; preparations for MLR1 APTS/DPTS testing underway.
  
- Work on the overall detector design optimisation and layout proceeds with conceptual studies supported by simulations and by engineering work to start soon.

